

**1. Scope**

Wafer Connector pitch 2.5mm series

This specification covers the Wafer Connector FWF25018/FWF25019 Series

**2. Connector Dimensions**

Refer to the drawing.

**3. Material**

Housing:Refer to the drawing UL94V-0

Color :White

Contacts Terminal:Brass

Plating:Tin-Plated all

**4. Accommodated P.C.B Layout**

Refer to the drawing.

**5. Rating**

Operating Voltage(Max.)                      250V AC/DC

Current Rating(Max.)                          3A DC/AC

Operating Temperature                      -25°C -- +85°C(Including terminal temperature rise)

## 6. Performance

### Electrical Performance

Contact Resistance	20mΩ Max	Mate connectors, Measure by dry circuit. 20mV Max. 10mA Mated Length : 50mm (AWG. #22) (Based upon JIS C5402 5.4)
Insulation Resistance	1000MΩ Min	Mate applicable connectors and apply 500V DC between adjacent terminal or ground. (Based upon JIS C5402 5.2/MIL-STD-202 method 302 Cond.B)
Dielectric Strength	No breakdown and flashover	Mate applicable connectors, apply 1000V AC(rms) for 1 minute between adjacent terminal or ground. (Based upon JIS C5402 5.1/MIL-STD-202 Method 301)
Contact resistance on Crimped Portion	20mΩ Max	Crimp the maximum applicable wire on to the terminal, measure by dry circuit, 20mV MAX, 10mA Wire Length : 50mm (AWG. #22)

### Mechanical Performance

Mechanical Performance

Insert and withdrawal force	Refer to paragraph 7	Insert and withdraw connectors at the speed rate of 25±3mm/minute.	
Crimping pull out force	AWG #22	4.0 kgf Min	Fix the crimped terminal,apply axial pull out force on the wire at the speed rate of 25±3mm/minute. (Based upon JIS C5402 6.22)
	AWG #24	3.0 kgf Min	
	AWG #26	2.0 kgf Min	
	AWG #28	1.5 kgf Min	
	AWG #30	0.8 kgf Min	
Terminal Insertion force	1.5kgf Max	Insert the crimped terminal into the housing at the speed rate of 25±3mm/minute.	
Terminal/Housing Retention force	2.0kgf Max	Apply axial pull out force at the speed rate of 25±3mm/minute on the terminal assembled in the housing	
Pin retention force	2.0kgf Min	Apply axial push force at a speed of 25±3mm/minuted on the contact pin assembled in the base wafer	

### Environmental Performance and others

Repeated insertion/withdrawal	When mated up to 30 cycles repeatedly by the rate of 10 cycles per minute	Contact Resistance	40 mΩ Max
Temperature Rise	Apply rated current load on mated connector in series-connection. Measure change of temperature on contact using thermocouples for 4 hours. (Based upon UL 1977)	Temperature rise	30°C Max

Vibration	Mate connectors and subject to the following vibration conditions,for period of 2 hours in each of 3 mutually perpendicular axes,passing DC 1mA during the test . Amplitude:1.52mm P-P Frequency:10-55-10Hz in 1 munute Duration:2 hours in each of X.Y.Z axe (Based upon MIL-STD-202 method 201)	Appearance	No Damage
		Contact Resistance	40mΩ Max
		Discontinuity	1μsec Max

Shock	50G , 3 strokes in each X,Y,Z axlals. (Based upon JIS C0041)	Appearance	No Damage
		Contact Resistance	40mΩ Max
		Discontinuity	1μsec Max

Heat Resistance	Mated connector shall be placed in a oven for 96±4 hours at +85±2°C (Based upon JIS C5402 7.8)	Appearance	No Damage
		Contact Resistance	40mΩ Max

Cold Resistance	Mated connector shall be placed in a temperature chamber for 96±4 hours at -25±3°C (Based upon JIS C5402 7.9)	Appearance	No Damage
		Contact Resistance	40mΩ Max

Humidity	Mated connector shall be placed in a humidity chamber on the following conditions . Temperature:40±2°C Relative humidity:90~95% Duration:96 Hours (Based upon JIS C0022/MIL-STD-202 Method 103B Cond.B)	Appearance	No Damage
		Contact Resistance	40mΩ Max
		Dielectric strength	No Breakdown
		Insulation Resistance	100MΩ Min

Temperature Cycling	Mated connector shall be set to temperature cycling for 5 cycles of which 1cycle consists of : 1.+25°C-----3minutes 2.-25°C-----30minutes 3.+25°C-----3minutes 4.+85°C-----30minutes (Based upon JIS C5402 7.2)	Appearance	No Damage
		Contact Resistance	40mΩ Max
		Dielectric strength	No Breakdown
		Insulation Resistance	100MΩ Min

Salt Spray	Mated connector shall be placed in a salt spray chamber on the following conditions. Salt solution density: 5±1% Temperature: 35±2°C Duration: 24±4 Hours (Based upon JIS C5402 7.1/MIL-STD-202 Method 101D Cond.B)	Appearance	No Damage
		Contact Resistance	40mΩ Max

Solderability	Tip of solder tails and fitting nails into the molten solder (held at $230 \pm 5^{\circ}\text{C}$ ) up to 0.1mm from the bottom of the housing for $3 \pm 0.5$ seconds.	Solder Wetting	95% of immersed area must show no voids nor pin holes
---------------	-------------------------------------------------------------------------------------------------------------------------------------------------------------------------	----------------	-------------------------------------------------------

Resistance to Soldering Heat	Mated connector shall be dipped on solder bath for $5 \pm 0.5\text{sec}$ temperature : $260 \pm 5^{\circ}\text{C}$	Appearance	No Damage
------------------------------	-----------------------------------------------------------------------------------------------------------------------	------------	-----------

## 7. Insertion/Withdrawal Force

Circuits	Unit	Insertion Force (Max.)	Withdrawal Force(Min.)		
		Initial	Initial	10th	30th
1	kgf	0.5	0.2	0.2	0.2
2	kgf	2.5	0.8	0.6	0.6
3	kgf	3.0	1.0	0.8	0.8
4	kgf	3.5	1.2	0.9	0.9
5	kgf	4.0	1.2	0.9	0.9
6	kgf	4.5	1.4	1.0	1.0
7	kgf	5.0	1.4	1.0	1.0
8	kgf	5.5	1.6	1.2	1.2
9	kgf	6.0	1.6	1.2	1.2
10	kgf	6.5	1.8	1.4	1.4
11	kgf	7.0	1.8	1.4	1.4
12	kgf	7.5	2.0	1.6	1.6
13	kgf	8.0	2.0	1.6	1.6
14	kgf	8.5	2.2	1.8	1.8
15	kgf	9.0	2.4	2.0	2.0
16	kgf	9.5	2.6	2.0	2.0
17	kgf	10.0	2.8	2.2	2.2
18	kgf	10.5	3.0	2.4	2.2
19	kgf	11.0	3.2	2.6	2.4
20	kgf	11.5	3.4	2.0	2.6